



Material Content Data Sheet



Sales Product Name		ICE2HS01G		Issued		25. January 2018		
MA#		MA001379936						
Package		PG-DSO-20-45		Weight*		587.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.580	0.44	0.44	4392	4392
leadframe	inorganic material	phosphorus	7723-14-0	0.047	0.01		81	
	non noble metal	zinc	7440-66-6	0.190	0.03		323	
	non noble metal	iron	7439-89-6	3.797	0.65		6465	
wire	non noble metal	copper	7440-50-8	154.185	26.25	26.94	262510	269379
	noble metal	gold	7440-57-5	0.572	0.10	0.10	974	974
	encapsulation	organic material	carbon black	1333-86-4	0.838	0.14		1427
encapsulation	plastics	epoxy resin	-	38.563	6.57		65655	
	inorganic material	silicondioxide	60676-86-0	379.758	64.65	71.36	646563	713645
leadfinish	non noble metal	tin	7440-31-5	4.543	0.77	0.77	7735	7735
plating	noble metal	silver	7440-22-4	0.800	0.14	0.14	1362	1362
glue	plastics	epoxy resin	-	0.369	0.06		628	
	noble metal	silver	7440-22-4	1.107	0.19	0.25	1885	2513
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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